

# WETTING TESTER

# SWB-2

## SPECIAL FEATURES

The entire procedure, from Flux application (w/Flux Temp. Control Function) to Measurement End is automated. Reducing unstable measurement results, and user error. Complies with the Wetting test method according to JIS Z3198 (Lead Free Solder Test Method) standards.

Easily change Solder and Flux when necessary.

Efficiently analyze data with the exclusive PC software.

An optional cover allows for wetting evaluation in a N<sub>2</sub> environment.



## JAPANESE STANDARD

### Automatic Measurement

**(Flux Application, Removal & Measurement) :**

**JIS Z3198-4 or C0053**

**(Solder Bath) : JEITA ET7401**

## OVERSEAS STANDARD

**ISO 9455-16**

**(Solder Bath)**

**IEC 60068-2-54 & 60068-2-69**

**ANSI J-STD-003, MIL-STD-883 (Method 2022.2)**

**IPC-TM-650 (2.4.14.2)**

## SPECIFICATIONS

Load Sensor	Electro-Balance Sensor (EBS)
Load Sensor Measuring Range & Accuracy	100 mN—50 mN ± ~0.12 mN
Load Sensor Resolution	0.01 mN
Temp. Sensor Measuring Range & Accuracy	0—350 ± 3
Insertion Time, Depth & Speed	1—200 sec. 0.01—20.0 mm (0.01 mm step) 0.1—30 mm/s
Solder Tem. Setting	Room Temp.—330
N <sub>2</sub> Measurement (Optional)	Oxygen Concentration : 500 ppm max.
Power Supply	AC 100V
Outer Dimension	300mm (W) x 330mm (D) x 370mm (H)
Weight	Approx. 16.0 kg

\* The specifications are subject to change without notice.

Spiral Viscometer  
Soldering Process Devices

### Malcomtech International

26200 Industrial Blvd

Hayward, CA 94545

Tel: (510) 293-0580

E-mail : info@malcomtech.com